2SD2134

Silicon NPN epitaxial planar type

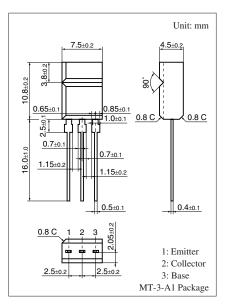
For low-frequency driver , high power amplification Complementary to 2SB1414

Features

- \bullet Excellent collector current I_C characteristics of forward current transfer ratio h_{FE}
- \bullet High transition frequency $f_{\rm T}$
- A complementary pair with 2SB1414, is optimum for the driverstage of a 60 W to 100 W output amplifier.

Symbol	Rating	Unit					
V _{CBO}	150	V					
V _{CEO}	150	V					
V _{EBO}	5	V					
I _C	1	А					
I _{CP}	1.5	А					
P _C	1.5	W					
Tj	150	°C					
T _{stg}	-55 to +150	°C					
	Symbol V _{CBO} V _{CEO} V _{EBO} I _C P _C T _j	Symbol Rating V _{CBO} 150 V _{CEO} 150 V _{EBO} 5 I _C 1 I _{CP} 1.5 P _C 1.5 T _j 150					

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

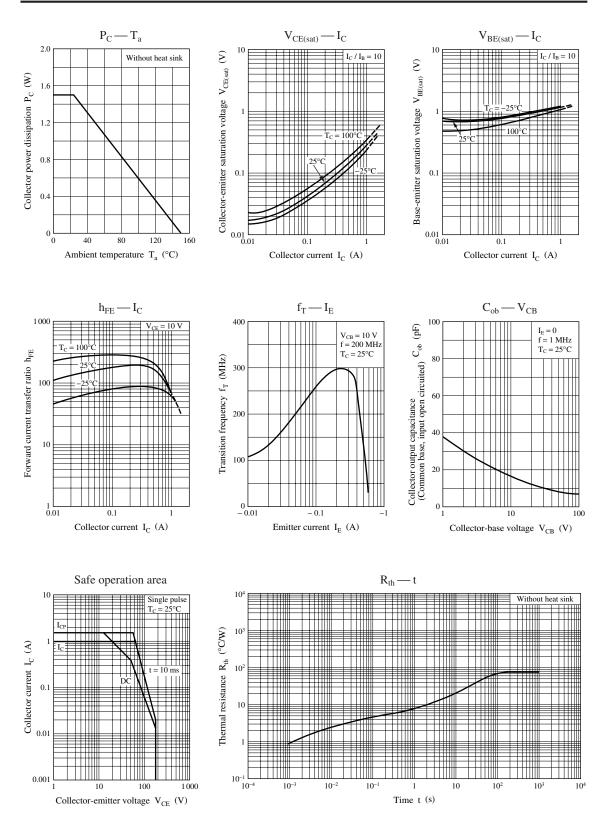
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 100 \ \mu A, I_{\rm B} = 0$	150			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \ \mu A, I_C = 0$	5			V
Forward current transfer ratio	h _{FE1} *	$V_{CE} = 10 \text{ V}, I_C = 150 \text{ mA}$	90		220	_
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_C = 500 \text{ mA}$	50			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}$		0.5	2.0	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}$		1.0	2.0	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		20		pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R
h _{FE1}	90 to 155	130 to 220

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